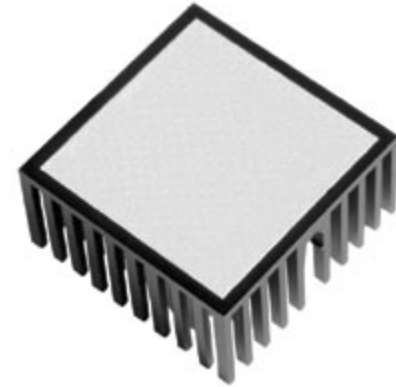




BOARD LEVEL COOLING – 3740

3740 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative Image Only.



ORDERING INFORMATION

Part Number	Device Type
374024B00035G	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Tape
Thermal Interface Material	T411 Chomerics Tape for All

Property	Details
Heat Sink Width (mm)	23.00
Heat Sink Length (mm)	23.00
Heat Sink Height (mm)	10.00
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

